

What is claimed is:

1. A driving apparatus of a plasma display panel (PDP), comprising a multi-chip module in which at least one control chip having a control circuit for controlling the PDP, and at least one memory are mounted on a single package,

wherein the multi-chip module is mounted on a printed circuit board (PCB) of a control board.

2. The driving apparatus according to claim 1, wherein the package is a ball grid type.

3. The driving apparatus according to claim 1, wherein a control signal generated from the multi-chip module is transmitted to each driving unit via the PCB.

4. A driving apparatus of a PDP, comprising:

a control board provided with a multi-chip module in which at least one control chip having a control circuit for controlling the PDP, and at least one memory are mounted on a single package;

a plurality of driving units for generating and applying a driving signal corresponding to a control signal generated from the control board; and

a PDP for displaying an image by a plasma discharge according to the driving signal applied from each of the plurality of driving units.

5. The driving apparatus according to claim 4, wherein the package is a ball grid type.

6. The driving apparatus according to claim 4, wherein the control board is provided with a printed circuit board (PCB) on which at least one package is mounted.

7. The driving apparatus according to claim 4, wherein the control chip is an ASIC type having a control circuit.

8. The driving apparatus according to claim 4, wherein the multi-chip module is mounted on the PCB.

9. A method for fabricating a driving apparatus of a plasma display panel, the method comprising the steps of:

forming holes and circuit patterns in and on a plurality of substrates;

laminating the plurality of substrates to form a single package such that the circuit patterns formed on the respective substrates are electrically connected with each other through the holes;

mounting at least one control chip and at least one memory on the package; and

coating a coating material on a front surface of the package and attaching solder balls on a rear surface of the package to complete a multi-chip module.

10. The method according to claim 9, further comprising the step of filling a conductive material into the holes formed in each of the plurality of substrates.

11. The method according to claim 9, wherein when the plurality of substrates are laminated, the circuit patterns are electrically connected by the holes filled with the conductive material.

12. The method according to claim 9, wherein the solder balls are attached to be in contact with the conductive material filled in the holes formed on the rear surface of the package.